

100V Input, 1.5A Current Limit, Step-down Converter

Features

- 1.5A current limit
- · ESOP-8 package
- · 95% Peak Efficiency
- · Up to 92% duty cycle
- 1µA shutdown current
- 0.8V voltage reference
- · 150 kHz Fixed Frequency
- Peak Current mode control
- · 1A continuous load current
- · Thermal shutdown Function
- · 9V to 100V input voltage range
- 400µA operating quiescent current
- 120V 400-mΩ high-side MOSFET
- · 150ms Hiccup mode short circuit protection Function

Applications

- Charger in vehicle
- Battery Chargers
- · Charger in vehicle

Pin Configuration

1 EN SW 8 2 VIN GND BOOT 7 NC 6

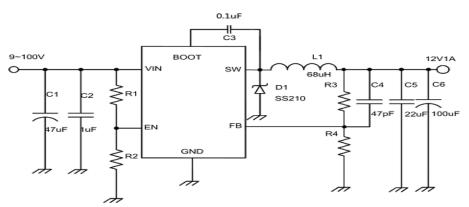
FΒ

5

GND

4

Typical Application



General Description

The FS1062 is a high voltage, non-synchronous step-down converter operates over a wide range input voltage 9V to 100V. The FS1062 integrates a 120V $400m\Omega$ high-side mosfet. The FS1062 delivers 1A continuous load current with up to 95% efficiency. The FS1062 operates with fixed frequency peak current control with built-in compensation eliminates the need for external components. Cycle-by-cycle current limit in high-side mosfet protects the converter in an overload condition. Hiccup mode protection is triggered if the over-current condition has persisted for longer than the present time. The FS1062 exhibits protection features that protect the load from faults like under-voltage, over-current and over-temperature. The FS1062 is available in an ESOP-8 package.

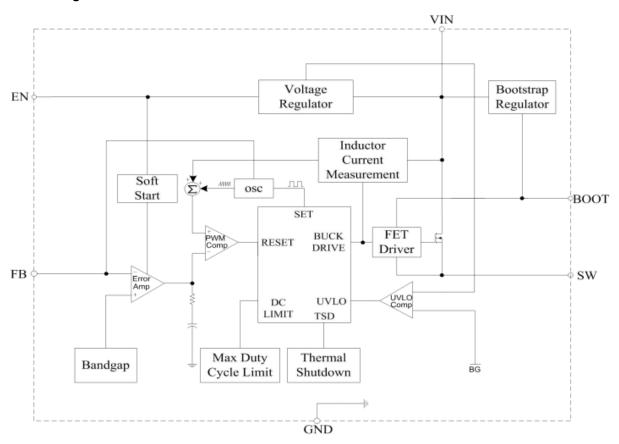
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Pin Configuration

| Pin | Symbol | Description |
|-----------|--------|--|
| (ESOP-8L) | | |
| 1 | EN | Enable input. Pull EN below the specified threshold to shut down the FS1062. Pull EN above the |
| | | specified threshold to enable the FS1062. |
| 2 | VIN | Input supply. VIN supplies power to all of the internal control circuitry, both BOOT regulators, and |
| | | the high-side switch. |
| 3,4,9 | GND | Ground. GND should be placed as close to the output capacitor as possible to avoid the |
| | | high-current switch paths. Connect the exposed pad to GND plane for optimal thermal |
| | | performance |
| 5 | FB | Feedback. FB is the input to the voltage hysteretic comparator. The average FB voltage is |
| | | maintained at 800mV by loop regulation. |
| 6 | NC | No Connection |
| 7 | воот | Bootstrap. BOOT is the positive power supply for the internal, floating, high-side MOSFET driver. |
| | | Connect a bypass capacitor between BOOT and SW. |
| 8 | SW | Switch node. SW is the output from the high-side switch. A low forward voltage schottky rectifier |
| | | to ground is required. The rectifier must be placed close to SW to reduce switching spikes. |

Block Diagram





• Absolute Maximum Ratings

| Parameter | Symbol | Ratings | Unit | |
|--------------------------------------|--------------------------|--|--------------|--|
| SW, EN, VIN Voltage | V_{SW}, V_{EN}, V_{IN} | -0.3 to 120 | | |
| FB Voltage | V_{FB} | -0.3 to 7 | V | |
| BOOT Voltage | V _{BOOT} | V _{SW} -0.3 to V _{SW} +7 | | |
| Junction Temperature | T_J | 150 | | |
| Storage Temperature Range | T _{stg} | -55 to + 150 | $^{\circ}$ C | |
| Lead Temperature (Soldering 10 sec.) | | 260 | | |
| Human Body Model | ESD | 2 | kV | |

Electrical Characteristics

| Parameter | Symbol | Test Conditions | Min | Тур | Max | Unit |
|-------------------------------------|------------------------|-------------------------|-----|------|-----|------------|
| Input Voltage Range | V _{IN} | | 9 | | 100 | |
| UVLO | V _{START} | | | 8 | | V |
| UVLO Hysteresis | V _{UVLO1} | | | 0.3 | | |
| Shutdown supply current | I _{SHUT} | EN=0V | | 9 | | |
| Input Quiescent Current | IQ | V _{FB} =1V | | 500 | | uA |
| Enable threshold voltage | V _{EN} | | | 2.2 | | |
| Enable threshold voltage Hysteresis | V _{UVLO2} | | | 0.2 | | |
| FB Reference Threshold | V _{FB} | | | 0.8 | | V |
| Feedback short voltage | V _{FB(short)} | | | 0.35 | | |
| Feedback short voltage Hysteresis | V _{FB2} | | | 0.42 | | |
| Switching frequency | F | I _{OUT} =500mA | | 150 | | KHz |
| Maximum Duty Cycle | D _{MAX} | V _{IN} =12V | | 92 | | % |
| Current Limit Threshold | I _{PEAK} | | | 1.5 | | Α |
| On-resistance | R _{DSON} | V _{IN} =18V | | 400 | | mΩ |
| Thermal shutdown Temp | T _{SD} | | | 150 | | $^{\circ}$ |
| Thermal shutdown Temp Hysteresis | T _{SH} | | | 30 | | $^{\circ}$ |

Note: exceeding the range specified by the rated parameters will cause damage to the chip, and the working state of the chip beyond the range of rated parameters cannot be guaranteed. Exposure outside the rated parameter range will affect the reliability of the chip.

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Typical Characteristics (At T_A=25^oC, V_{IN}=48V, V_{OUT}=12V, Unless Otherwise Noted)

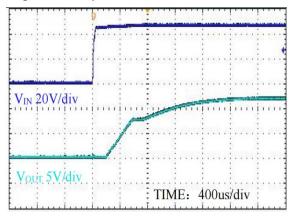
Figure1 EN Start up EN 5V/div

TIME: 400us/div

V_{IN}=48V EN=5V

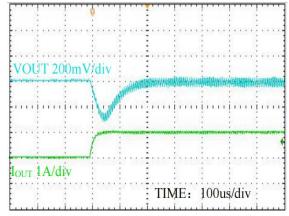
Vour 5V/div

Figure3 Start up



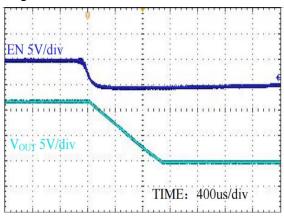
V_{IN}=48V I_{OUT}=0A

Figure5 Load Transient



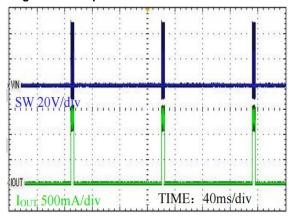
I_{OUT}=10mA~1A V_{IN}=48V

Figure2 EN Turn off



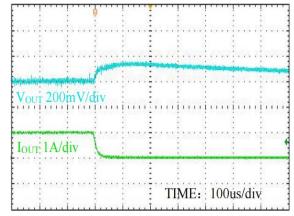
V_{IN}=48V EN=5V

Figure4 Start up



 $V_{IN}=48V$

Figure6 Load Transient

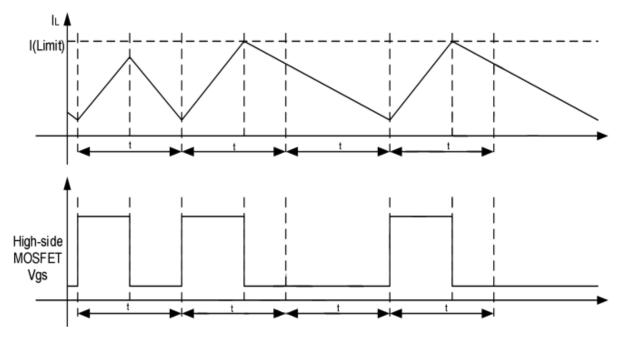


I_{OUT}=10mA~1A V_{IN}=48V

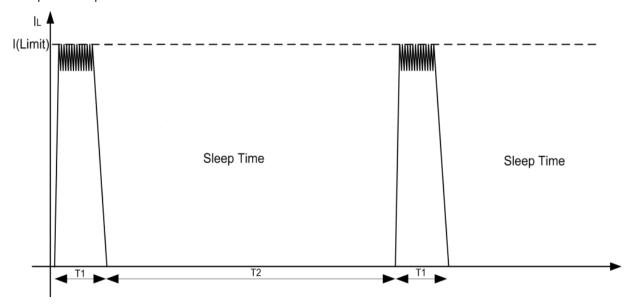


Applications Information

Over-current Protection: TheFS1062 implements current-mode control which uses the internal COMP voltage to control the turn on and the turnoff of the high-side mosfet on a cycle-by-cycle basis. During each cycle, the switch current and the current reference generated by the internal COMP voltage are compared. When the peak switch current intersects the current reference the high-side switch turns off.



Hiccup mode: If an output overload condition occurs for more than the hiccup wait time, which is programmed for 512 switching cycles(T1), the device shuts down and restarts after the hiccup time of 16384 cycles(T2). The hiccup mode helps to reduce the device power dissipation under severe over-current conditions.



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C1: This capacitor's purpose is to supply most of the switch current during the on-time, and limit the voltage ripple at VIN.To allow for the capacitor's tolerance, temperature effects, and voltage effects, a 47 μ F, capacitor is used.

C2: This capacitor helps avoid supply voltage transients and ringing due to long lead inductance at VIN. A low ESR, 1µF ceramic chip capacitor is recommended, located close to the FS1062.

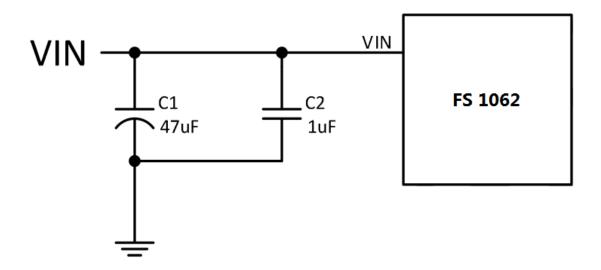


Figure7 The capacitor on the VIN

L1: The inductance is determined based on the switching frequency, load current, inductor ripple current, and the minimum and maximum input voltages designated VIN(min) and VIN(max), respectively. The peak inductor current during an overload condition is limited to 3 A nominal. Use the value of 68µH,5A to prevent saturation.

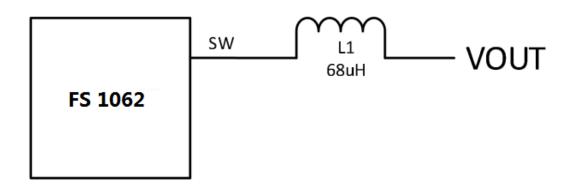


Figure8 The inductor on the choice

D1:A power Schottky diode is recommended. Ultra-fast recovery diodes are not recommended as the high speed transitions at the SW pin may inadvertently affect the IC's operation through external or internal EMI. The important parameters are reverse recovery time and forward voltage. The reverse recovery time determines how long the reverse current surge lasts with each turn-on of the internal buck switch. The forward voltage drop affects efficiency. The diode's reverse voltage rating must be at least as great as the maximum input voltage, plus ripple and transients, and its current rating must be at least as great as the maximum current limit specification.

C4/C5:The output capacitor filters the inductor ripple current and provides a source of charge for transient load conditions. The best performance is typically obtained using ceramic or polymer electrolytic type components. Typical tradeoffs are that the ceramic capacitor provides extremely low ESR to reduce the output ripple voltage and noise spikes. In order to meet output ripple specification, we should choose a ceramic capacitor of 22uF and a polymer electrolytic capacitor of 100uF.

R1/R2:The output voltage (VOUT) is programmed by two external resistors as shown in the Figure 15. The regulation point can be calculated as follows:

$$VOUT = 0.8 \times (R1 + R2) / R2$$

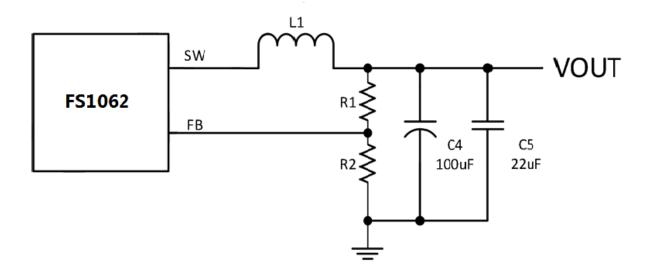
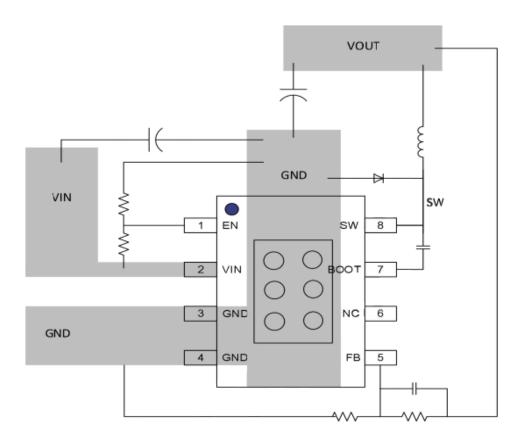


Figure9 Output Capacitors and Output Configuration

Layout



IMPORTANT NOTICE

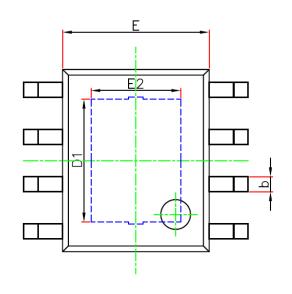
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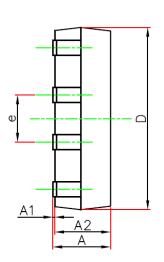


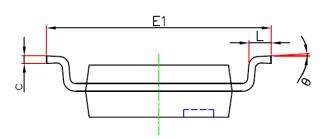


Package Information

E-SOP8







| Symbol | Dimensions Ir | n Millimeters | Dimensions In Inches | | |
|--------|---------------|---------------|----------------------|-------|--|
| | Min. | Max. | Min. | Max. | |
| Α | 1.300 | 1.700 | 0.051 | 0.067 | |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 | |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 | |
| b | 0.330 | 0.510 | 0.013 | 0.020 | |
| С | 0.170 | 0.250 | 0.007 | 0.010 | |
| D | 4.700 | 5.100 | 0.185 | 0.201 | |
| D1 | 3.202 | 3.402 | 0.126 | 0.134 | |
| E | 3.800 | 4.000 | 0.150 | 0.157 | |
| E1 | 5.800 | 6.200 | 0.228 | 0.244 | |
| E2 | 2.313 | 2.513 | 0.091 | 0.099 | |
| е | 1.270(| BSC) | 0.050(BSC) | | |
| L | 0.400 | 1.270 | 0.016 | 0.050 | |
| θ | 0° | 8° | 0° | 8° | |